

1mm MINI EDGE CARD SOCKET MEC1 SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn or Au over 50µ" (1,27µm) Ni

Operating Temp Range:

-55°C to +125°C

Current Rating:

2A @ 80°C ambient

Voltage Rating: 300 VAC

Insertion Depth:

(5,84mm) .230" to (8,13mm) .320"

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

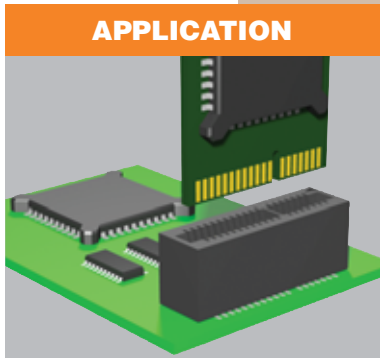
SMT Lead Coplanarity:

(0,10mm) .004" max (05-20)

(0,15mm) .006" max (30-70)

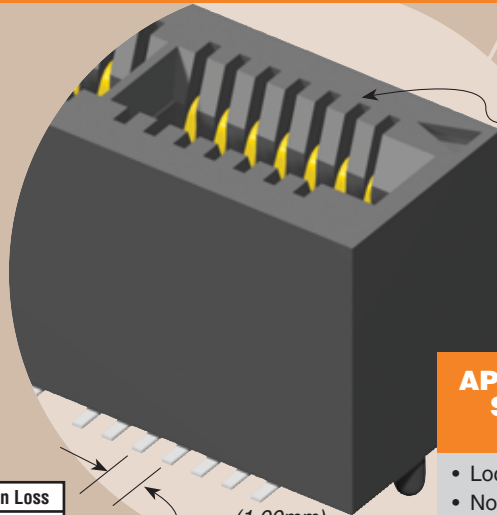


Mates with: (1,60mm) .062" card



1mm MEC1	Rated @ -3dB Insertion Loss
9,19mm Stack Height	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

Mates with (1,60mm) .062" card



APPLICATION SPECIFIC OPTION

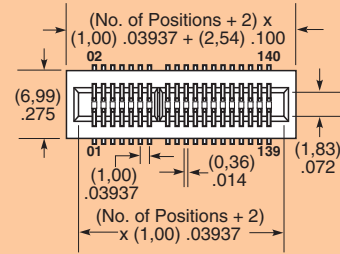
- Locking Clip
 - Non-polarized
- Call Samtec.



05, 08, 20, 30, 40, 50, 60, 70

-F = Gold flash on contact, Matte tin on tail
 -L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail

-A = Alignment Pin Metal or plastic at Samtec discretion.
 -K = (7,87mm) .310" DIA Polyimide film Pick & Place Pad
 -TR = Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM